

Description

TPSeal® M3670 is a new generation metallocene Medium Density Polyethylene (mMDPE) with hexene as comonomer.

TPSeal® M3670 is intended for the manufacture of rotomoulded items and available in black, in pellets or in powder.

It is also available under a natural colour (TPSeal® M3671).

Main Characteristics

Its specific molecular structure ensures:

- ✓ Efficient binding with fuel barrier product such as Polyamide
- ✓ Excellent foaming properties

Application

Suitable for monolayer and multi-layer with foam technology.

Fuel tank production, with very low permeability. Structural parts. Water sports application.

Properties

Property	Method	Unit	Typical value (*)
Density (**)	ISO 1183	g/cm ³	0.941
Melt Flow Rate (190°C-2.16kg)	ISO 1133/D	g/10min	3.5
Melting Temperature	ISO 11357	°C	126
Tensile modulus	ISO 527	MPa	650
Tensile strength @yield	ISO 527	MPa	18

(*) Data not intended for specification purposes

(**) Based on natural resin

Processing conditions

It is recommended to keep product dry prior use for production.

Handling and storage

Please refer to the material safety data sheet (MSDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the MSDS of our product.

MSDS may be obtained from the website: <http://www.polymers.total.com/>

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